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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74HC237

3-to-8-line Decoder/Demultiplexer with Address Latch



ADE-205-469 (Z)
1st. Edition
Sep. 2000

Description

The HD74HC237 decodes a three-bit Address to one-of-eight active-high outputs. The device has a transparent latch for storage of the Address. Two Chip Selects, one active-low and one active-high, are provided to facilitate the demultiplexing, cascading, and chip-selecting functions.

The demultiplexing function is accomplished by using the Address inputs to select the desired device output, and then by using one of the Chip Selects as a data input while holding the other one active.

The HD74HD237 is the noninverting version of the HD74HC137.

Features

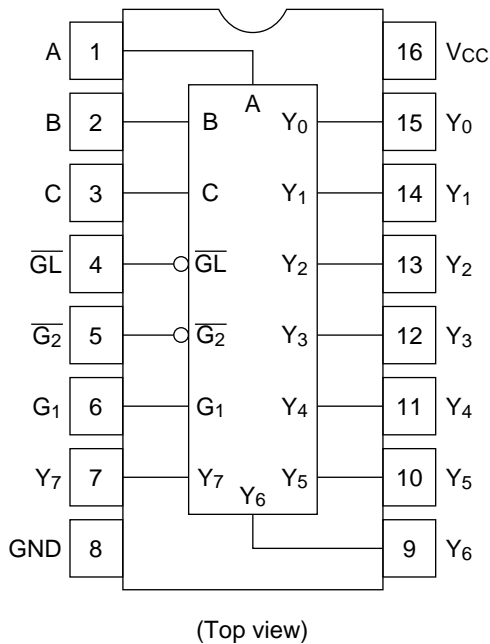
- High Speed Operation: t_{pd} (Data to Y) = 19 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

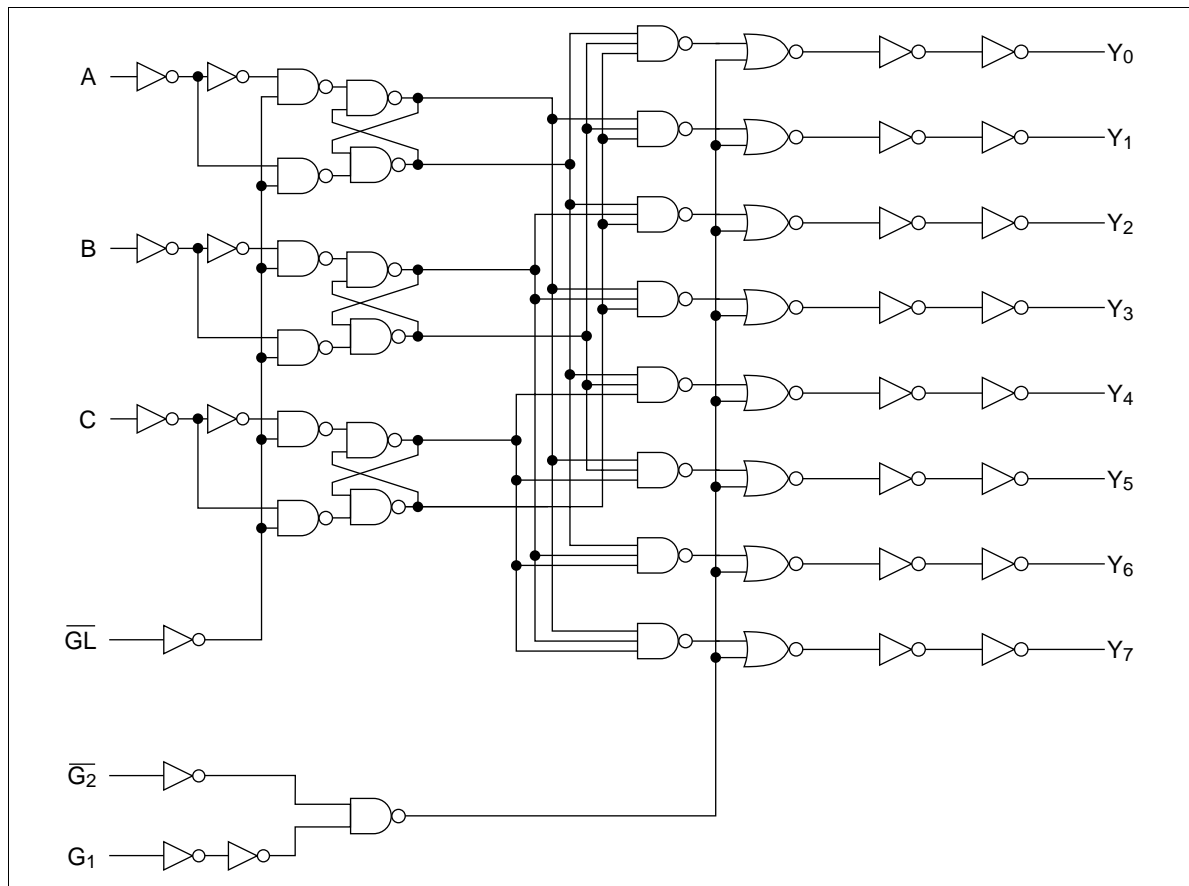
Inputs

Enable			Select			Outputs							
$\overline{G_L}$	G_1	$\overline{G_2}$	C	B	A	Y_0	Y_1	Y_2	Y_3	Y_4	Y_5	Y_6	Y_7
X	X	H	X	X	X	L	L	L	L	L	L	L	L
X	L	X	X	X	X	L	L	L	L	L	L	L	L
L	H	L	L	L	L	H	L	L	L	L	L	L	L
L	H	L	L	L	H	L	H	L	L	L	L	L	L
L	H	L	L	H	L	L	L	H	L	L	L	L	L
L	H	L	L	H	H	L	L	L	H	L	L	L	L
L	H	L	H	L	L	L	L	L	L	H	L	L	L
L	H	L	H	L	H	L	L	L	L	L	H	L	L
L	H	L	H	H	L	L	L	L	L	L	L	H	L
L	H	L	H	H	H	L	L	L	L	L	L	L	H
H	H	L	X	X	X	Output corresponding to stored address H; all others L							

Pin Arrangement



Logic Diagram



DC Characteristics

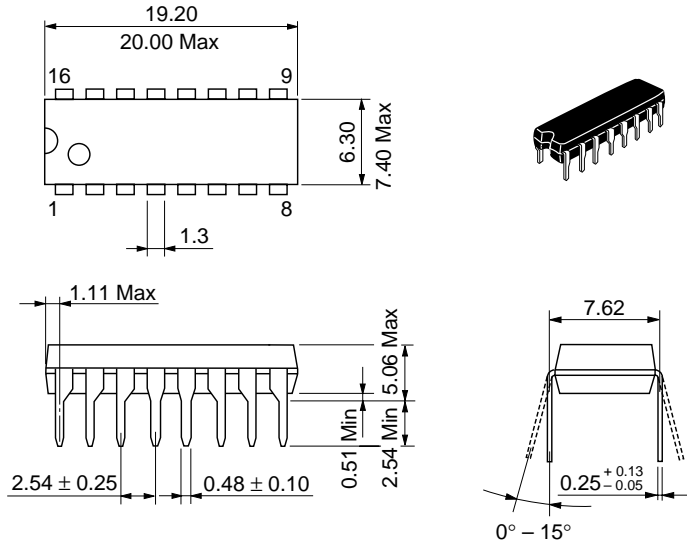
Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Propagation delay time	t_{PLH}	2.0	—	—	185	—	230	ns	Data to Y
		4.5	—	19	37	—	46		
		6.0	—	—	31	—	39		
		2.0	—	—	145	—	180	ns	\overline{G}_2 to Y
		4.5	—	14	29	—	36		
		6.0	—	—	25	—	31		
		2.0	—	—	145	—	180	ns	G_1 to Y
		4.5	—	14	29	—	36		
		6.0	—	—	25	—	31		
		2.0	—	—	190	—	240	ns	\overline{GL} to Y
		4.5	—	21	38	—	48		
		6.0	—	—	32	—	41		
Pulse width	t_w	2.0	80	—	—	100	—	ns	
		4.5	16	8	—	20	—		
		6.0	14	—	—	17	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	
		4.5	5	-4	—	5	—		
		6.0	5	—	—	5	—		
Setup time	t_{SU}	2.0	75	—	—	95	—	ns	
		4.5	15	4	—	19	—		
		6.0	13	—	—	16	—		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

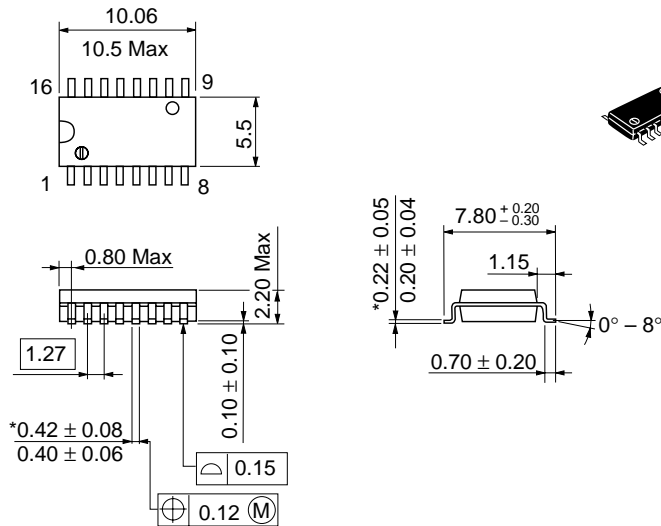
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

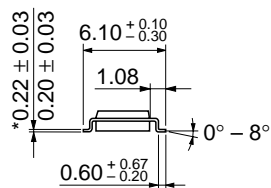
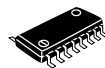
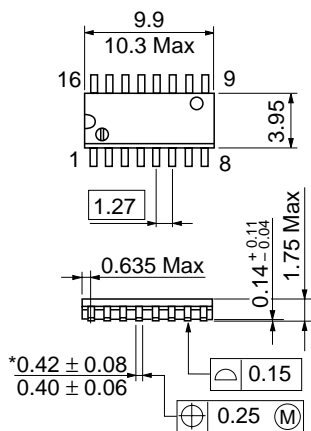
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

Unit: mm



*Dimension including the plating thickness
 Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

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